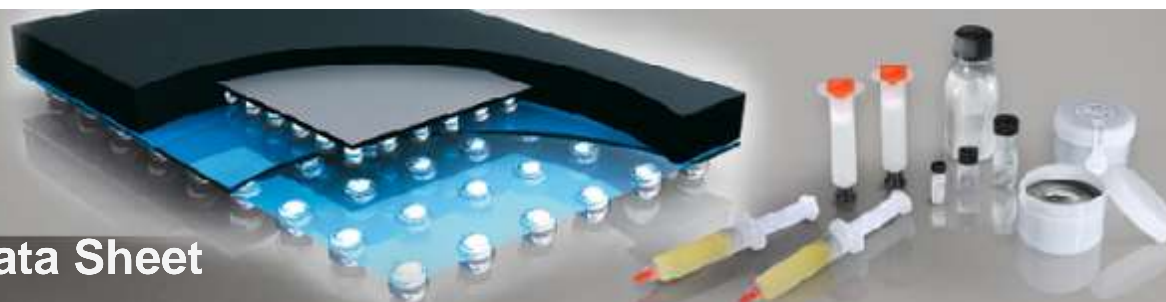

Technical Data Sheet

SOP 91123 P SAC305-Series (Scale Up)

Description

The SOP 91123 Solder Paste series, is a lead free, no-clean solder paste that promotes outstanding wetting and minimizes soldering defects. The flux system is specifically optimized for lead free solder alloys. This formula provides superior performance on a variety of surface finishes and leaves a clear residue after reflow. It is developed for J-STD-004 L0 classification and contains no halogens or halides.

Key Benefits

- Anti-Capillary effect beneath QFP components
- Good high-volume print capability
- Halogen Zero

Product Code and Alloy

Code				Powder Properties			Application		
Paste	Alloy	Metal Content	Powder Type	Particle Size	Alloy	Melting Point	Stencil Printing	Dipping	Dispensing
SOP 91123	SAC305	89,25	4	25 - 45 µm	SnAg3,0Cu0,5	217°C	☑	☐	☐
							☐	☐	☐
							☐	☐	☐
							☐	☐	☐

Flux Activity

No Clean	Water Washable	ISO 9454-1:1990 [DIN EN 29454-1:1993]	J-STD-004A:2004	Bellcore GR-78-Core [Issue 1:1997]	Siemens Norm [SN 59650:1998]
☑	☐	1.2.2.C	REL0	not tested	not tested

Halogen Content

Halogen Free ☐

Halogen Free - Tolerances from IEC 61249-2-21: Cl or Br < 900 ppm, total < 1500 ppm; measured according BS EN 1458

Halogen Zero - No Halogen added in the Flux: ☑

Halogen Zero - Tolerance: Halogen < 50 ppm; measured according BS EN 14582

Paste Conditioning

Take paste from fridge: Before opening the package leave paste 2 hours at room temperature so that paste warms up. Do not open jar/cartridge while paste is cold to prevent condensation of moisture on the paste. Do not heat the paste.
Before use of paste jar: To obtain uniform, stable viscosity stir paste for 1 to 2 min, using a stainless steel or chemically resistive plastic spatula.

Reflow

Peak temperature: 20 - 30°C above the melting temperature of the alloy. Time above melting temperature: 30 to 60 seconds.

Cleaning

After reflow flux residues may remain on the circuit and do not need to be washed. For cleaning of wet paste or if desired for cleaning of flux residues Zestron and Vigon cleaners can be used – see separate cleaning recommendations.

Storage

Store the solder paste in tightly-sealed containers and avoid exposure to sunlight and high humidity.
Max. expiration date: Please refer to the expiry date on the lable of the packaged product. Store refrigerated @ 2 - 10°C

Contact www.heraeus-contactmaterials.com / Product Management SMT

Version Scale Up: MICROBOND SOP 91123 P SAC305 Series

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